25/40 G TOSA

Fraunhofer
Heinrich Hertz Institute

AT A GLANCE

25/40 G Electroabsorption Modulator with integrated Laser (EML), 25 G Directly Moduled Laser (DML), Customized selection of chips

Features

- SSMF pigtailed optical output (FC/APC)
- Temperature control by TEC
- V-connector for RF input
- 9-pin micro-D adapter for dc-inputs and TEC-control
- Optional: matching resistor

Applications

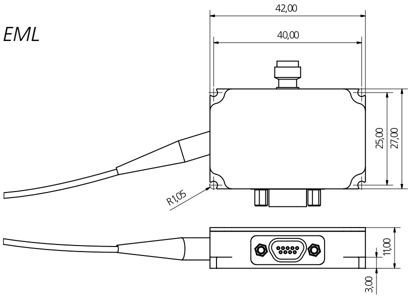
- Evaluation of EML/DML chip performance
- System tests

Technical background

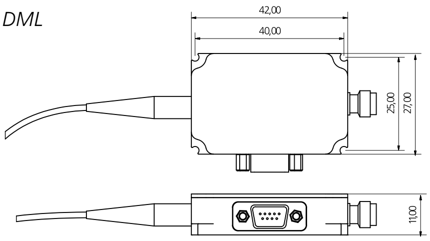
- InGaAlAs-MQW devices
- n-InP substrate

Dimensions

EML



DML

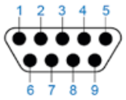


Electrical connectors

V connector EAM	Assignment and Description
Signal	Control of EAM bias (-) and RF input
Ground	EAM ground, common ground

V connector Laser	Assignment and Description
Signal	Control of DFB laser (+) and RF input
Ground	DFB laser ground, common ground

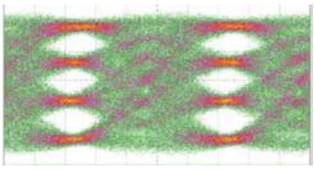
Micro-D Pin	Assignment and Description
1	NC
2	EML: DFB laser (+), control DFB DML: NC
3	EML: DFB laser ground, common ground with EAM DML: NC
4	NTC Thermistor*), T-sensor
5	NTC Thermistor*), T-sensor
6	NC
7	NC
8	TEC (-), control of Peltier
9	TEC (+), control of Peltier



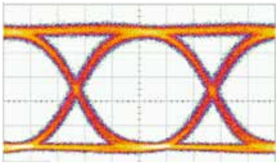
9 pin

**) 10K3CG3, Betatherm*

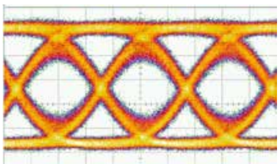
Examples (EML)



PAM4 34 Gbaud



40 Gb/s



64 Gb/s

Dr. Martin Möhrle
Photonic Components

Phone +49 30 31002-724
martin.moehrle@hhi.fraunhofer.de

Fraunhofer Heinrich Hertz Institute
Einsteinufer 37, 10587 Berlin
Germany

www.hhi.fraunhofer.de/pc